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PATENT

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IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re application of: Agarwal et al.

Application No. 10/002,779

Filed: October 29, 2001

For: METHODS FOR FORMING AND
INTEGRATED CIRCUIT STRUCTURES
CONTAINING RUTHENIUM AND TUNGSTEN
CONTAINING LAYERS

Examiner: David Vu

Date: January 6, 2003

Art Unit: 2818

CERTIFICATE OF MAILING

I hereby certify that this paper and the documents referred to as being attached or enclosed herewith are being deposited with the United States Postal Service on January 6, 2003 as First Class Mail in an envelope addressed to: COMMISSIONER FOR PATENTS, WASHINGTON, D.C. 20231.

Attorney for Applicant

INFORMATION DISCLOSURE STATEMENT
PURSUANT TO 37 C.F.R. § 1.97(b)

COMMISSIONER FOR PATENTS
WASHINGTON, DC 20231

Sir:

Listed on the accompanying form PTO-1449 and enclosed herewith are several English-language documents. Applicants respectfully request that these documents be listed as references cited on the issued patent.

This Information Disclosure Statement is being filed after the mailing date of a first Office action on the merits, and before the mailing date of a final Office action, a Notice of Allowance, or an action that otherwise closes prosecution, and a \$180.00 fee under 37 C.F.R. § 1.17(p) may be charged to Deposit Account No. 02-4550. If the Patent Office

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determines that an additional fee is required for to file this Information Disclosure Statement, please charge any such fees to Deposit Account No. 02-4550. Two copies of this Information Disclosure Statement are enclosed.

Respectfully submitted,

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